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and  
said semiconductor light receiving element being configured such that light which is transmitted through a region having a light transmittance different from that of said light absorbing layer, is projected within a 2- dimensional projected area of said semiconductor light receiving element which is obtained when said semiconductor light receiving element is projected onto the plane on which said element is to be mounted.

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7. (amended) A semiconductor light receiving element having a light absorbing layer on a plane generally parallel to a plane with which said element is mounted on a substrate, said semiconductor light receiving element being configured such that light which is transmitted through a region having a light transmittance different from that of said light absorbing layer, is projected inside a 2- dimensional projected area of said light receiving element which is formed when said semiconductor light receiving element is projected onto the plane on which said element is to be mounted and an image of a positioning marker is also projected inside said projected area onto which the light transmitted through the region having a light transmittance different from that of said light absorbing layer is projected.

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10. (amended) An optical module, wherein said semiconductor light receiving element is claimed in any one of claims 1 to 7 is optically coupled to an optical fiber and mounted on a same substrate.

11. (amended) An optical module, wherein a semiconductor laser, an optical fiber, and said semiconductor light receiving element as claimed in any one of claims 1 to 7 optically coupled to at least one of said semiconductor laser and optical fiber, are mounted on a same substrate.

as 12. (amended) The optical module as claimed in Claim 10, wherein said semiconductor light receiving element mounted on said substrate is configured by being packaged with either ceramic or resin.

13. (amended) The optical module as claimed in Claim 10, wherein an electronic circuit is further mounted on said substrate, said electronic circuit being configured by being packaged with either ceramic or resin.

14. (amended) An optical transmission apparatus, wherein said optical module as claimed in Claim 10 and an electronic circuit are mounted on a same board, said electronic circuit being connected to said optical module and executing at least

AS  
cond either processing of a sending processing and a receiving  
processing of a light signal. B

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Please add the following new claims:

--17. An optical module, wherein said semiconductor light receiving element is claimed in Claims 8 is optically coupled to an optical fiber and mounted on a same substrate.

18. An optical module, wherein said semiconductor light receiving element is claimed in claim 9 is optically coupled to an optical fiber and mounted on a same substrate.

A6 19. An optical module, wherein a semiconductor laser, an optical fiber, and said semiconductor light receiving element as claimed in claim 8 optically coupled to at least one of said semiconductor laser and optical fiber, are mounted on a same substrate. B

20. An optical module, wherein a semiconductor laser, an optical fiber, and said semiconductor light receiving element as claimed in claim 9 optically coupled to at least one of said semiconductor laser and optical fiber, are mounted on a same substrate.

21. The optical module as claimed in Claim 11, wherein said semiconductor light receiving element mounted on said substrate is configured by being packaged with either ceramic or resin.

22. The optical module as claimed in Claim 11, wherein an electronic circuit is further mounted on said substrate, said electronic circuit being configured by being packaged with either ceramic or resin.

Ab 23. The optical module as claimed in Claim 17, wherein said semiconductor light receiving element mounted on said substrate is configured by being packaged with either ceramic or resin.

24. The optical module as claimed in Claim 18, wherein said semiconductor light receiving element mounted on said substrate is configured by being packaged with either ceramic or resin.

25. The optical module as claimed in Claim 19, wherein said semiconductor light receiving element mounted on said substrate is configured by being packaged with either ceramic or resin.

26. The optical module as claimed in Claim 20, wherein said semiconductor light receiving element mounted on said substrate is configured by being packaged with either ceramic or resin.

27. The optical module as claimed in Claim 17, wherein an electronic circuit is further mounted on said substrate, said electronic circuit being configured by being packaged with either ceramic or resin.

Ab 28. The optical module as claimed in Claim 18, wherein an electronic circuit is further mounted on said substrate, said electronic circuit being configured by being packaged with either ceramic or resin.

29. The optical module as claimed in Claim 19, wherein an electronic circuit is further mounted on said substrate, said electronic circuit being configured by being packaged with either ceramic or resin.

30. The optical module as claimed in Claim 20, wherein an electronic circuit is further mounted on said substrate, said electronic circuit being configured by being packaged with either ceramic or resin.

31. An optical transmission apparatus, wherein said optical module as claimed in Claim 10, and an electronic circuit are mounted on a same board, said electronic circuit being connected to said optical module and executing at least either processing of a sending processing and a receiving processing of a light signal.

Ab 32. An optical transmission apparatus, wherein said optical module as claimed in Claim 11, and an electronic circuit are mounted on a same board, said electronic circuit being connected to said optical module and executing at least either processing of a sending processing and a receiving processing of a light signal.

33. An optical transmission apparatus, wherein said optical module as claimed in Claim 12, and an electronic circuit are mounted on a same board, said electronic circuit being connected to said optical module and executing at least either processing of a sending processing and a receiving processing of a light signal.

34. An optical transmission apparatus, wherein said optical module as claimed in Claim 13, and an electronic circuit are mounted on a same board, said electronic circuit

being connected to said optical module and executing at least either processing of a sending processing and a receiving processing of a light signal.

35. An optical transmission apparatus, wherein said optical module as claimed in Claim 17, and an electronic circuit are mounted on a same board, said electronic circuit being connected to said optical module and executing at least either processing of a sending processing and a receiving processing of a light signal.

ab 36. An optical transmission apparatus, wherein said optical module as claimed in Claim 18, and an electronic circuit are mounted on a same board, said electronic circuit being connected to said optical module and executing at least either processing of a sending processing and a receiving processing of a light signal.

37. An optical transmission apparatus, wherein said optical module as claimed in Claim 19, and an electronic circuit are mounted on a same board, said electronic circuit being connected to said optical module and executing at least either processing of a sending processing and a receiving processing of a light signal.